

Material Declaration Report



Package Type:	MQFP 160L (28x28mm)
Pericom Package Code:	MA160(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	5585.500
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	3
Peak Body Temp (C):	245C
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	12/18/2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	4838.9909	ASE-Malaysia	Silica Fused Epoxy Resin Phenolic Resin Epoxy, Cresol Novolac Carbon Black	60676-86-0 Proprietary Proprietary 29690-82-2 1333-86-4	88.0000 5.0000 4.5000 2.0000 0.5000	4258.3120 241.9495 217.7546 96.7798 24.1950
LEADFRAME	688.3848		Copper Nickel Silver Silicon Magnesium	7440-50-8 7440-02-0 7440-22-4 7440-21-3 7439-95-4	95.1400 3.2000 0.7600 0.7250 0.1750	654.9293 22.0283 5.2317 4.9908 1.2047
SILICON DIE	20.1019		Silicon (Si) Non-hazardous Metal	7440-21-3 Proprietary	99.1920 0.8080	19.9395 0.1624
DIE ATTACH EPOXY	1.4184		Silver Epoxy Resin gamma-Butyrolactone	7440-22-4 Proprietary 96-48-0	84.0000 8.0000 8.0000	1.1914 0.1135 0.1135
GOLD WIRE	6.0844		Gold(Au) Impurities	7440-57-5 -	99.9900 0.0100	6.0838 0.0006
SOLDER PLATING	30.5197		Tin (Sn) Impurity	7440-31-5 -	99.9900 0.0100	30.5166 0.0031

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
		<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
		O	O	O	O	O	O
<p>O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.</p> <p>X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.</p>							